

In the Specification

Please amend the following paragraph(s) of the specification as noted.

[0011] Wire bonds 46 and 46A are standard wire bonds formed between their respective attachment points or points of contact between bonding pads 25 and leads 44. Each of the wire bonds 46 and 46A are formed using a wire bonding tool that attaches or welds the bonding wire to a first attachment point on one of the bonding pads 25. The bonding wire is then fed through a capillary that moves to a second attachment point on one of the leads 44. The wire bonding tool is programmed to locate the first and second attachment points and loop the bonding wire to an optimal height determined by the physical characteristics of a semiconductor die, package and bonding wire.

[0019] FIG. 1B is an isometric view showing details of a portion of integrated circuit 10 and inductor 50. As indicated above, inductor 50 is formed with coil 52 in order to increase its inductance while maintaining a high quality factor and a low package profile. Coil 52 typically has a cylindrical contour, but may also have an elliptical or polygonal shape as well, depending on the fabrication method. Note that in this embodiment, inductor 50 is extended laterally from a line 54 through its attachment points on bonding pads 51 and 53. Inductor 50 is self-supporting, but in some applications its bonding wire material may be alloyed or doped with beryllium or other material to increase rigidity to maintain its shape and position.